

Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
L1	780	resputter\$3 or (re-sputter\$3) or (re adj sputter\$3)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/04/07 14:01
L2	9337	sputter\$ adj etch\$3	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/04/07 14:01
L3	9943	1 or 2	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/04/07 14:01
L4	35647	multicomponent or (multi-component) or (multi adj component)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/04/07 14:01
L5	1167415	target or cathode	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/04/07 14:02
L6	263	4 near4 5	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/04/07 14:02
L7	8	3 and 6	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/04/07 14:14
L8	4897	bias\$3 adj (substrate or wafer)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/04/07 14:14

L9	3	6 and 8	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/04/07 14:14
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